



FUJI XPF-W Multi Purpose SMT Pick And Place Machines For PCB Production

Our Product Introduction

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Basic Information

- Place of Origin: Japan
- Brand Name: FUJI
- Model Number: XPF-W
- Minimum Order Quantity: 1 pcs
- Price: USD+negotiable+pcs
- Packaging Details: 1800*2000*1650mm
- Delivery Time: 1-7 days
- Payment Terms: T/T
- Supply Ability: 1+pcs+per days



Product Specification

- Model: FUJI XPF-W
- PCB Size: L50mm X W50mm To L686mm X W508mm
- PCB Thickness: 0.4–6.5mm
- PCB Loading Time: 3.5 Sec
- External Dimension: L1500 X W1762.5 X H1422.5mm
- Weight: Approx. 1860kg without MFU Mounted
- Highlight: Multi Purpose SMT Pick And Place Machines, PCB SMT Pick And Place Machines, SMT PCB Pick And Place Machine



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Product Description

The FUJI XPF-L/W High-speed Multi-Purpose Mounter is a state-of-the-art machine designed to enhance productivity and flexibility in electronics manufacturing. It excels in high-speed component placement while being adaptable for a wide range of surface-mount technology (SMT) applications. This mounter is well-suited for modern, complex production environments, offering both high speed and precision in placing electronic components on printed circuit boards (PCBs). Below is a detailed overview of its key functions and features:

Key Functions:

1. High-Speed Component Placement:

The XPF-L/W is equipped with high-speed heads that enable rapid and precise component placement. It can handle a variety of component sizes, from small chip components to larger ICs. The machine is designed to optimize throughput while maintaining accuracy, making it ideal for mass production environments that require fast cycle times and high yields.

2. Versatility in Handling Different Components:

One of the standout features of the XPF series is its ability to handle a wide range of components, including 0201 (metric) microchips, odd-shaped components, and larger devices like connectors. This makes the machine extremely flexible for different types of SMT jobs, whether it's producing simple boards or complex, densely populated PCBs.

3. On-the-Fly Component Centering:

The machine uses a high-precision vision system to perform real-time component centering during placement. This ensures that components are placed accurately even at high speeds, reducing the need for manual intervention and minimizing placement errors. This function is essential for maintaining high production quality, especially in fast-paced environments.

4. Multi-Function Head:

The XPF-L/W comes with a multi-function head that can switch between different tasks, such as placement of standard components, odd-form parts, or large connectors. This eliminates the need for separate machines or manual intervention, as the mounter can perform various tasks in one setup. This feature significantly improves productivity and reduces downtime.

5. Automatic Feeder Exchange:

This mounter supports automatic feeder exchange, which minimizes machine stoppages and allows for continuous production. The feeder carts can be swapped without interrupting the operation, allowing for quick and efficient material replenishment. This feature is particularly beneficial in environments where different production runs need to be processed back-to-back.

6. Flexible PCB Handling:

The XPF-L/W is capable of handling a wide range of PCB sizes, from small boards to larger, more complex panels. Its conveyor system can be adjusted to accommodate different PCB dimensions, making it highly adaptable to various production requirements.

7. Nozzle Changer System:

The mounter features an automatic nozzle changer that can store multiple nozzle types and exchange them as needed during operation. This system enhances the machine's ability to place a wide range of component types without the need for manual intervention, thus increasing overall productivity and flexibility.

8. Advanced Software Integration:

The XPF-L/W integrates seamlessly with FUJI's proprietary software, which provides full control over the machine's functions, programming, and monitoring. The software offers real-time tracking, production analysis, and automatic optimization for placement efficiency. It also supports remote monitoring and diagnostics, allowing operators to oversee production from virtually anywhere.

9. Non-Stop Operation with Dynamic Load Balancing:

The machine is designed for continuous operation, utilizing dynamic load balancing to evenly distribute work across multiple heads. This ensures that no individual head becomes a bottleneck, resulting in higher throughput and more consistent production. Load balancing also helps extend the life of the machine by preventing excessive wear on any one part.

10. Hybrid Placement Capability:

The XPF-L/W supports both chip shooting and fine-pitch placement in one unit, making it a hybrid system capable of handling a diverse range of SMT components. This flexibility reduces the need for multiple machines and enhances production line efficiency, especially when dealing with high-mix, low-volume production runs.

Key Features:

1. Compact Design:

Despite its advanced capabilities, the XPF-L/W has a compact footprint that makes it suitable for factories where space is a premium. Its design allows it to be easily integrated into existing production lines without requiring significant modifications to the layout.

2. High Precision and Accuracy:

With advanced motion control systems and precision placement heads, the XPF-L/W ensures high levels of accuracy. This is critical for placing tiny components on high-density boards, where even the smallest misalignment can result in product failures.

3. Scalable for High Mix/Low Volume Production:

The XPF-L/W is perfect for companies that handle a mix of different product types. Its fast setup times, automatic changeover functions, and versatile component handling capabilities make it ideal for environments where frequent product changes are

necessary. This helps reduce downtime and maximizes production efficiency.

4. Wide Range of Component Size Handling:

The mounter is designed to handle components ranging from 0201 microchips to large ICs and connectors. Its wide range of compatible component sizes makes it an all-in-one solution for various PCB assembly requirements.

5. User-Friendly Interface:

The machine is equipped with an intuitive, easy-to-navigate user interface that simplifies setup, operation, and maintenance. Operators can easily access machine settings, program new production runs, and monitor performance in real time.

6. Energy-Efficient Design:

The XPF-L/W incorporates energy-efficient technologies that reduce power consumption without compromising performance. This helps lower operating costs and supports sustainability initiatives in electronics manufacturing.

7. Built-in Error Detection and Correction:

To ensure the highest production quality, the machine is equipped with built-in error detection systems that can identify and correct misplacements or other errors during the production process. This minimizes rework and reduces waste, contributing to cost savings and higher yields.

8. Modular Design for Easy Maintenance:

The XPF-L/W is designed with a modular structure, making it easy to perform maintenance and upgrades. Key components can be quickly replaced or serviced, minimizing downtime and ensuring long-term reliability.

9. Wide Operating Range:

This mounter can operate under a wide range of conditions, handling various types of boards and components. Its robust design ensures consistent performance even in challenging production environments.

10. Compliance with Industry Standards:

The FUJI XPF-L/W complies with the latest industry standards for SMT equipment, ensuring it meets the rigorous demands of electronics manufacturing, including quality control, precision, and safety.

Conclusion:

The FUJI XPF-L/W High-speed Multi-Purpose Mounter is a highly advanced, flexible, and reliable machine that can adapt to a wide range of production environments. Its combination of speed, precision, and versatility makes it an ideal solution for manufacturers looking to optimize their SMT processes, reduce downtime, and improve overall productivity. Whether you're dealing with high-volume production or frequently changing product lines, this mounter offers the features and capabilities to meet your needs.

FUJI XPF-W: Versatile SMT Machine for High-Mix, Low-Volume PCB Production | GSSMT, FUJI XPF-L/W mounter, FUJI high-speed mounter, FUJI XPF-L/W SMT machine, FUJI XPF-L/W placement accuracy, FUJI multi-purpose mounter, FUJI XPF-L/W component feeder, FUJI SMT equipment XPF-L/W, FUJI XPF-L/W PCB assembly, FUJI XPF-L/W features, FUJI XPF-L/W specifications, FUJI XPF-L/W performance review, FUJI XPF-L/W maintenance, FUJI XPF-L/W vs other mounters, FUJI XPF-L/W high-speed placement, FUJI XPF-L/W vision system, FUJI XPF-W: Versatile SMT Machine for High-Mix, Low-Volume PCB Production



FUJI XPF-W High Speed Multi-Purpose Mounter specification:

Model	FUJI XPF-W	
PCB size	L50mm x W50mm to L686mm x W508mm	
PCB Thickness	0.4–6.5mm	
Auto-Tool	Revover Auto-Tool	Single Nozzle
Number of Auto-Tool held in auto-tool station	3	8
Supported Parts	0402 (01005) to 20x20mm Maximum, height: 3.0 mm	1005(0402) to 45x150 (45x45)mm Maximum, height: 25.4 mm
Machine Test	0.144 sec/component, 25000cph	0.40 sec/component, 9000cph
Small Chip Parts Placing Accuracy	+/-0.050mm CPK \geq 1.00 +/-0.066mm CPK \geq 1.33	+/-0.040mm CPK \geq 1.00 +/-0.053mm CPK \geq 1.33
QFP Placing Accuracy	+/-0.040mm CPK \geq 1.00 +/-0.053mm CPK \geq 1.33	+/-0.030mm CPK \geq 1.00 +/-0.040mm CPK \geq 1.33
PCB Loading Time	3.5 sec	
External dimension	L1500 x W1762.5 x H1422.5mm (Transport height: 900mm; not include the Signal tower)	
Weight	Approx. 1860kg (without MFU mounted)	